

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3684858

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MASAKAZU WATANABE	01/07/2016
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Street Address:	5005 E. MCDOWELL ROAD
Internal Address:	MAILDROP A700
City:	PHOENIX
State/Country:	ARIZONA
Postal Code:	85008
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14983863
CORRESPONDENCE DATA	
Fax Number:	(602)244-3169
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	6022443574
Email:	patents@onsemi.com
Correspondent Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Address Line 1:	5005 E. MCDOWELL ROAD
Address Line 2:	MAILDROP A700
Address Line 4:	PHOENIX, ARIZONA 85008
ATTORNEY DOCKET NUMBER:	ONS01830PPP01
NAME OF SUBMITTER:	MICHELLE A. SMOJVER
SIGNATURE:	/MICHELLE A. SMOJVER/
DATE SIGNED:	01/07/2016
Total Attachments: 3	
source=ONS01830PPP01_20160107_ExecutedAssignment#page1.tif	
source=ONS01830PPP01_20160107_ExecutedAssignment#page2.tif	
source=ONS01830PPP01_20160107_ExecutedAssignment#page3.tif	

ASSIGNMENT & AGREEMENT

ONS01830PPP01

For good and valuable consideration, the receipt of which is hereby acknowledged, I,

Name _____ of (City/State/Country) _____
Masakazu WATANABE Ota-shi, JAPAN

have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto Semiconductor Components Industries, LLC (SCI), a limited liability Company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain inventions relating to improvements in

SEMICONDUCTOR LEADFRAMES AND PACKAGES WITH SOLDER DAMS AND RELATED METHODS

Attorney Docket No. ONS01830PPP01 described, illustrated, and claimed in an application for Letters Patent of the United States of America executed by us, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation, or reissue thereof.

I hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

適正・相当な対価を受領していることを認識し、私こと、

氏名 _____ 所在地 _____
Masakazu WATANABE Ota-shi, JAPAN

は、Phoenix, State of Arizona, United States of America に主たる所在地を有し、デラウェア州法に基づく有限会社たる Semiconductor Components Industries, LLC (SCI) とその継承者、譲受人および法定代理人に対して、我々が手続きを行ったアメリカ合衆国の特許証の申請において表現され、説明され、クレームされた、以下のインブルーメントに関係する特定の発明に関する(おける)完全な権利、権限および利権を、さらには当該申請および、申請に対する分割、延長、継続または再発行にともなって発行されることのある特許証における(対する)すべての権利、権限および利権とともに、売却、譲渡及び移転しており、かつこの書面をもって売却、譲渡及び移転することを認識する。

SEMICONDUCTOR LEADFRAMES AND PACKAGES WITH SOLDER DAMS AND RELATED METHODS
弁護士ドケット No. ONS01830PPP01

我々はさらに、SCI に対し、この書面をもって、アメリカ合衆国以外の国すべてに対して、発明及び特許証のための申請における完全な権利、権限および利権を売却、譲渡及び移転する。ここには外国における発明および特許証の申請に関連する国際協定や条約に基づく全ての権利が含まれる。さらに、我々は、SCI に対して、SCI の名において直接外国における特許証の申請を行う権利を授権し、かつ全ての国際協定や条約の規定に基づきアメリカ合衆国の特許証の申請日の優先権の主張を行うことを授権する。

We hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent upon the aforesaid application, division, extension,

Doc#: 122171v1

ASSIGNMENT & AGREEMENT

ONS01830PPP01

continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI.

I agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

I covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

我々は、本書をもって、アメリカ合衆国の特許商標庁長官に対し、SCI、その承継人、譲受人、法定代理人の単独使用ならびにこれらの者に代わりの使用のために、前述の申請、分割、延長、継続または再発行において SCI に特許証を発行することを、特許証が許可するかもしれない期間の満了日までに、同様に当該譲渡がなされなくとも我々が有しかつ与えられる満了日までに授權しかつ請願する。また、我々は外国の同等の機関に対して該当諸国における特許を SCI に対して発行することをこの書面をもって授權しかつ請願する。

我々は、要求に応じて、SCI に費用を請求することなく、しかし自己の負担において、あらゆるすべての世界中の国における発明に対する特許権を獲得しかつ維持するため、かつ SCI、SCI の承継人、譲受人、法定代理人または候補者にそれに対する権利を与えるため、全ての書面への署名、正当な誓約をとり、および必要となり、望まれる、便利的なすべての対応を行うことに合意する。

我々は、本書をもって得た利益と所有権には従前の譲渡、許諾、担保、ライセンス又はその他の負債がないことを、SCI、その承継人、譲受人および法定代理人に対して誓約する。

ASSIGNMENT & AGREEMENT

ONS01830PPP01

By (Inventor signature):

M. Watanabe.
Masakazu WATANABE

Witnessed by (Witness signature):

Masami Moteji

Printed name of Witness:

Masami Moteji

Signed and Witnessed on (date):

2016.01.07.